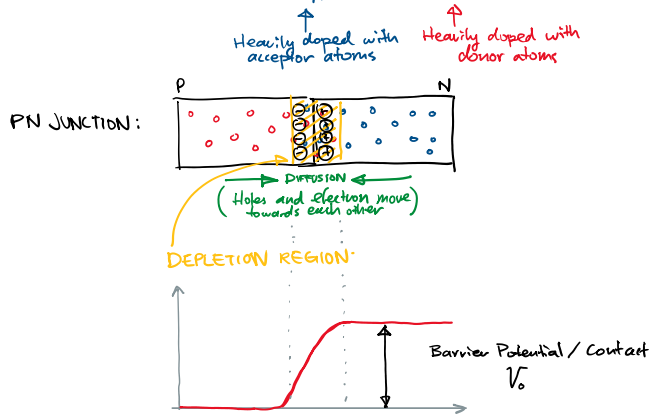
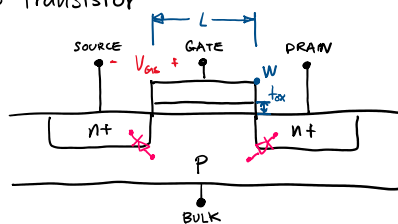


Devices are made of N-type and P-type semi-conductors

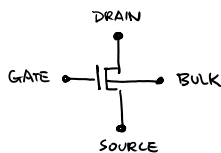


MOS Transistor

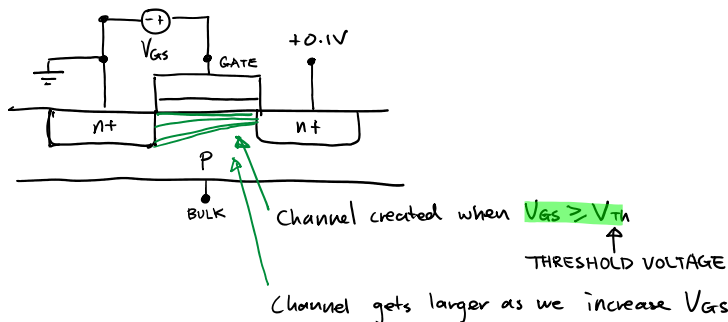


← this is like two diodes back-to-back
so external stimulus is required for conduction

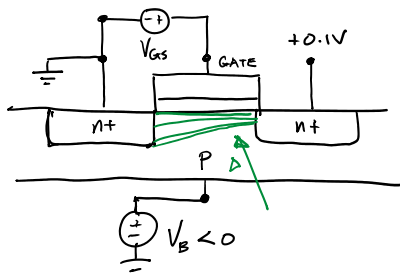
This configuration is N-P-N (NMOS) and is represented as a schematic as:



We need to apply voltage to the gate to create a channel for electrons to travel



We can change threshold voltage by applying negative voltage to BULK



$$V_{to} = V_{th} + \gamma \left(\sqrt{V_{GS} + 2\phi_F} - \sqrt{2\phi_F} \right)$$

Body-effect coefficient

$$\gamma = \frac{1}{C_{ox}} \sqrt{2q\epsilon_{si} N_A}$$

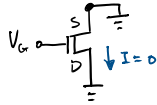
Current Calculation

Recall definition of current: charge moving over time

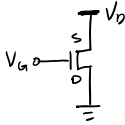
① When $V > V_{th}$... Change is a function of where in the depletion region (y) we're at.

Recall definition of current: charge moving over time

- ① When $V_{GS} > V_{TH}$: channel formed, but no current



- ② When $V_{DS} > 0$: carrier flows from S \rightarrow D



Charge is a function of where in the depletion region (y) we're at.

$$Q_n(y) = C_{ox} \cdot (V_{GS} - V(y) - V_T) \quad [C/m^2]$$

Charge/unit area

$$Q_d = W \cdot Q_n(y) \quad [C/m]$$

charge/length along direction of current (design parameter)

using def. of current: $I = Q_d \cdot v \quad [C/s]$

speed: $v = \mu E$

field: $E = \frac{dV(y)}{dy}$

combining all: $I_{DS} = W \cdot C_{ox} \cdot (V_{GS} - V(y) - V_T) \cdot \mu_n \cdot \frac{dV(y)}{dy}$

M A I C

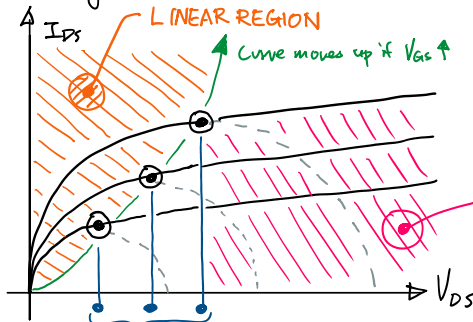
$$I_{DS} = \mu_n \frac{C_{ox}}{t_{ox}} \frac{W}{L} \cdot \left[(V_{GS} - V_T) \cdot V_{DS} - \frac{V_{DS}^2}{2} \right]$$

K'

I_{DS} has quadratic characteristics with respect to V_{DS}

I_{DS} has linear relationship to V_{GS}

Plotting I_{DS} vs. V_{DS}



I_{DS} at peak when $V_{DS} = V_{GS} - V_{TH}$

I_{DS} doesn't fall back down when $V_{DS} > V_{GS} - V_{TH}$
Because we've reached PINCH-OFF



So MOS is SATURATED. and I_{DS} is mostly flat w.r.t V_{DS}
(which makes a good current source)